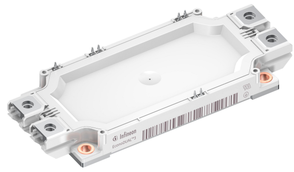
Final datasheet

EconoDUAL™3 module with Trench/Fieldstop IGBT4 and emitter controlled diode and PressFIT / NTC

Features



- Electrical features
  - V_{CES} = 1200 V
  - $I_{C\ nom}$ = 600 A / I_{CRM} = 1200 A
  - Low $V_{CE,sat}$
  - $T_{vj,op}$ = 150°C
  - $V_{CE,sat}$ with positive temperature coefficient
- Mechanical features
  - Direct-cooled base plate
  - Isolated base plate
  - High power density
  - Standard housing

Potential applications

- High-power converters
- Motor drives
- Servo drives
- UPS systems
- Wind turbines

Product validation

- Qualified for industrial applications according to the relevant tests of IEC 60747, 60749 and 60068

Description

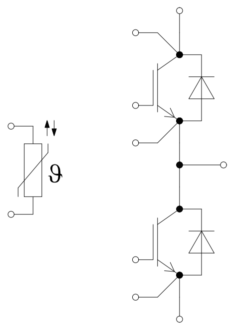


Table of contents

1 Package

Table 1 Insulation coordination

Parameter	Symbol	Note or test condition	Values	Unit
Isolation test voltage	V_{ISOL}	RMS, f = 50 Hz, t = 1 min	3.4	kV
Isolation test voltage NTC	$V_{ISOL(NTC)}$	RMS, f = 50 Hz, t = 1 min	3.4	kV
Material of module baseplate			Cu	
Internal isolation		basic insulation (class 1, IEC 61140)	Al_2O_3	
Creepage distance	$d_{Creep\ nom}$	terminal to baseplate, nom., (PD2, IEC 60664-1, Ed. 3.0)	> 15	mm
Creepage distance	$d_{Creep\ min}$	terminal to baseplate, min., (PD2, IEC 60664-1, Ed. 3.0)	14.7	mm
Creepage distance	$d_{Creep\ nom}$	terminal to terminal, nom., (PD2, IEC 60664-1, Ed. 3.0)	12.1	mm
Creepage distance	$d_{Creep\ min}$	terminal to terminal, min., (PD2, IEC 60664-1, Ed. 3.0)	11.5	mm
Clearance	$d_{Clear\ nom}$	terminal to baseplate, nom.	> 12.5	mm
Clearance	$d_{Clear\ min}$	terminal to baseplate, min.	12.5	mm
Clearance	$d_{Clear\ nom}$	terminal to terminal, nom.	10.0	mm
Clearance	$d_{Clear\ min}$	terminal to terminal, min.	9.6	mm
Comparative tracking index	*CTI*		> 200	
Relative thermal index (electrical)	*RTI*	housing	140	°C

Table 2 Characteristic values

Parameter	Symbol	Note or test condition		Values			Unit
				Min.	Typ.	Max.	
Pressure drop in cooling circuit	Δp	$\Delta V/\Delta t$ = 10.0 dm³/min, 50% water / 50% ethylenglycol, T_F = 60 °C			65		mbar
Maximum pressure in cooling circuit	p					3	bar
Stray inductance module	L_{sCE}				20		nH
Module lead resistance, terminals - chip	$R_{CC'+EE'}$	T_F = 25 °C, per switch			1		mΩ
Storage temperature	T_{stg}			-40		125	°C
Mounting torque for module mounting	M	- Mounting according to valid application note	M5, Screw	3		6	Nm
Terminal connection torque	M	- Mounting according to valid application note	M6, Screw	3		6	Nm

(table continues...)

Table 2 **(continued) Characteristic values**

Parameter	Symbol	Note or test condition	Values			Unit
			Min.	Typ.	Max.	
Weight	G			345		g

2 IGBT, Inverter

Table 3 **Maximum rated values**

Parameter	Symbol	Note or test condition		Values	Unit
Collector-emitter voltage	V_{CES}		T_{vj} = 25 °C	1200	V
Continuous DC collector current	I_{CDC}	$T_{vj\,max}$ = 175 °C	T_F = 45 °C	600	A
Repetitive peak collector current	I_{CRM}	t_p limited by $T_{vj\,op}$		1200	A
Gate-emitter peak voltage	V_{GES}			±20	V

Table 4 **Characteristic values**

Parameter	Symbol	Note or test condition		Values			Unit
				Min.	Typ.	Max.	
Collector-emitter saturation voltage	$V_{CE\,sat}$	I_C = 600 A, V_{GE} = 15 V	T_{vj} = 25 °C		1.75	2.10	V
			T_{vj} = 125 °C		2.00		
			T_{vj} = 150 °C		2.05		
Gate threshold voltage	V_{GEth}	I_C = 22.8 mA, V_{CE} = V_{GE}, T_{vj} = 25 °C		5.20	5.80	6.40	V
Gate charge	Q_G	V_{GE} = ±15 V, V_{CC} = 600 V			4.4		µC
Internal gate resistor	R_{Gint}	T_{vj} = 25 °C			1.2		Ω
Input capacitance	C_{ies}	f = 1000 kHz, T_{vj} = 25 °C, V_{CE} = 25 V, V_{GE} = 0 V			37		nF
Reverse transfer capacitance	C_{res}	f = 1000 kHz, T_{vj} = 25 °C, V_{CE} = 25 V, V_{GE} = 0 V			2.05		nF
Collector-emitter cut-off current	I_{CES}	V_{CE} = 1200 V, V_{GE} = 0 V	T_{vj} = 25 °C			3	mA
Gate-emitter leakage current	I_{GES}	V_{CE} = 0 V, V_{GE} = 20 V, T_{vj} = 25 °C				400	nA
Turn-on delay time (inductive load)	t_{don}	I_C = 600 A, V_{CC} = 600 V, V_{GE} = ±15 V, R_{Gon} = 1.5 Ω	T_{vj} = 25 °C		0.160		µs
			T_{vj} = 125 °C		0.210		
			T_{vj} = 150 °C		0.210		
Rise time (inductive load)	t_r	I_C = 600 A, V_{CC} = 600 V, V_{GE} = ±15 V, R_{Gon} = 1.5 Ω	T_{vj} = 25 °C		0.090		µs
			T_{vj} = 125 °C		0.090		
			T_{vj} = 150 °C		0.100		

(table continues...)

Table 4 **(continued) Characteristic values**

Parameter	Symbol	Note or test condition		Values			Unit
				Min.	Typ.	Max.	
Turn-off delay time (inductive load)	t_{doff}	I_C = 600 A, V_{CC} = 600 V, V_{GE} = ±15 V, R_{Goff} = 1.5 Ω	T_{vj} = 25 °C		0.480		µs
			T_{vj} = 125 °C		0.610		
			T_{vj} = 150 °C		0.650		
Fall time (inductive load)	t_f	I_C = 600 A, V_{CC} = 600 V, V_{GE} = ±15 V, R_{Goff} = 1.5 Ω	T_{vj} = 25 °C		0.070		µs
			T_{vj} = 125 °C		0.110		
			T_{vj} = 150 °C		0.120		
Turn-on energy loss per pulse	E_{on}	I_C = 600 A, V_{CC} = 600 V, L_σ = 35 nH, V_{GE} = ±15 V, R_{Gon} = 1.5 Ω, di/dt = 5100 A/µs (T_{vj} = 150 °C)	T_{vj} = 25 °C		62.5		mJ
			T_{vj} = 125 °C		83		
			T_{vj} = 150 °C		90		
Turn-off energy loss per pulse	E_{off}	I_C = 600 A, V_{CC} = 600 V, L_σ = 35 nH, V_{GE} = ±15 V, R_{Goff} = 1.5 Ω, dv/dt = 3700 V/µs (T_{vj} = 150 °C)	T_{vj} = 25 °C		47		mJ
			T_{vj} = 125 °C		72		
			T_{vj} = 150 °C		79.5		
SC data	I_{SC}	V_{GE} ≤ 15 V, V_{CC} = 800 V, V_{CEmax}=V_{CES}-L_{sCE}*di/dt	t_P ≤ 10 µs, T_{vj}=150 °C		2400		A
Thermal resistance, junction to cooling fluid[1)]	R_{thJF}	per IGBT, $\Delta V/\Delta t$ = 10.0 dm³/min, 50% water / 50% ethylenglycol, T_F = 60 °C			0.0848		K/W
Temperature under switching conditions	$T_{vj\,op}$			-40		150	°C

1) Typical R_{thJF} value using the heat sink described in the relevant application note.

3 Diode, Inverter

Table 5 **Maximum rated values**

Parameter	Symbol	Note or test condition		Values	Unit
Repetitive peak reverse voltage	V_{RRM}		T_{vj} = 25 °C	1200	V
Continuous DC forward current	I_F			600	A
Repetitive peak forward current	I_{FRM}	t_P = 1 ms		1200	A
I^2t - value	I^2t	t_P = 10 ms, V_R = 0 V	T_{vj} = 125 °C	40000	A^2s
			T_{vj} = 150 °C	37600	

Table 6 **Characteristic values**

Parameter	Symbol	Note or test condition		Values			Unit
				Min.	Typ.	Max.	
Forward voltage	V_F	I_F = 600 A, V_{GE} = 0 V	T_{vj} = 25 °C		1.65	2.10	V
			T_{vj} = 125 °C		1.65		
			T_{vj} = 150 °C		1.65		
Peak reverse recovery current	I_{RM}	V_{CC} = 600 V, I_F = 600 A, V_{GE} = -15 V, -di_F/dt = 5100 A/µs (T_{vj} = 150 °C)	T_{vj} = 25 °C		290		A
			T_{vj} = 125 °C		420		
			T_{vj} = 150 °C		450		
Recovered charge	Q_r	V_{CC} = 600 V, I_F = 600 A, V_{GE} = -15 V, -di_F/dt = 5100 A/µs (T_{vj} = 150 °C)	T_{vj} = 25 °C		62		µC
			T_{vj} = 125 °C		115		
			T_{vj} = 150 °C		130		
Reverse recovery energy	E_{rec}	V_{CC} = 600 V, I_F = 600 A, V_{GE} = -15 V, -di_F/dt = 5100 A/µs (T_{vj} = 150 °C)	T_{vj} = 25 °C		22		mJ
			T_{vj} = 125 °C		44		
			T_{vj} = 150 °C		51		
Thermal resistance, junction to cooling fluid[1)]	R_{thJF}	per diode, ΔV/Δt = 10.0 dm^3/min, cooling fluid = 50% water / 50% ethylenglycol, T_F = 60 °C			0.124		K/W
Temperature under switching conditions	$T_{vj\,op}$			-40		150	°C

1) Typical R_{thJF} value using the heat sink described in the relevant application note.

4 NTC-Thermistor

Table 7 **Characteristic values**

Parameter	Symbol	Note or test condition	Values			Unit
			Min.	Typ.	Max.	
Rated resistance	R_{25}	T_{NTC} = 25 °C		5		kΩ
Deviation of R_{100}	$\Delta R/R$	T_{NTC} = 100 °C, R_{100} = 493 Ω	-5		5	%
Power dissipation	P_{25}	T_{NTC} = 25 °C			20	mW
B-value	$B_{25/50}$	$R_2 = R_{25} \exp[B_{25/50}(1/T_2 - 1/(298,15\ K))]$		3375		K
B-value	$B_{25/80}$	$R_2 = R_{25} \exp[B_{25/80}(1/T_2 - 1/(298,15\ K))]$		3411		K
B-value	$B_{25/100}$	$R_2 = R_{25} \exp[B_{25/100}(1/T_2 - 1/(298,15\ K))]$		3433		K

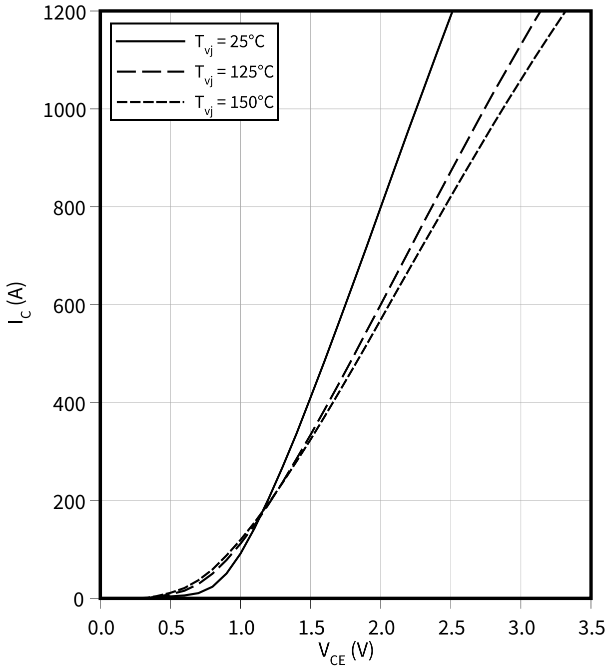
Note: *For an analytical description of the NTC characteristics please refer to AN2009-10, chapter 4.*

5 Characteristics diagrams

Output characteristic (typical), IGBT, Inverter

$I_C = f(V_{CE})$

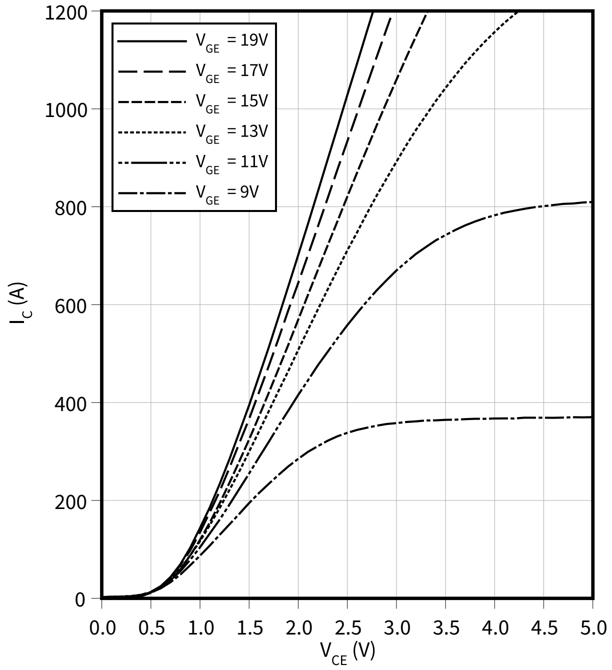
$V_{GE} = 15$ V



Output characteristic field (typical), IGBT, Inverter

$I_C = f(V_{CE})$

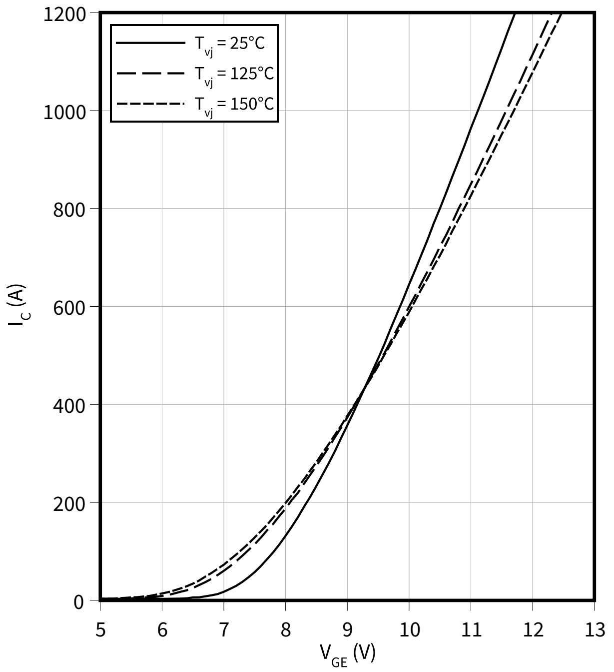
$T_{vj} = 150$ °C



Transfer characteristic (typical), IGBT, Inverter

$I_C = f(V_{GE})$

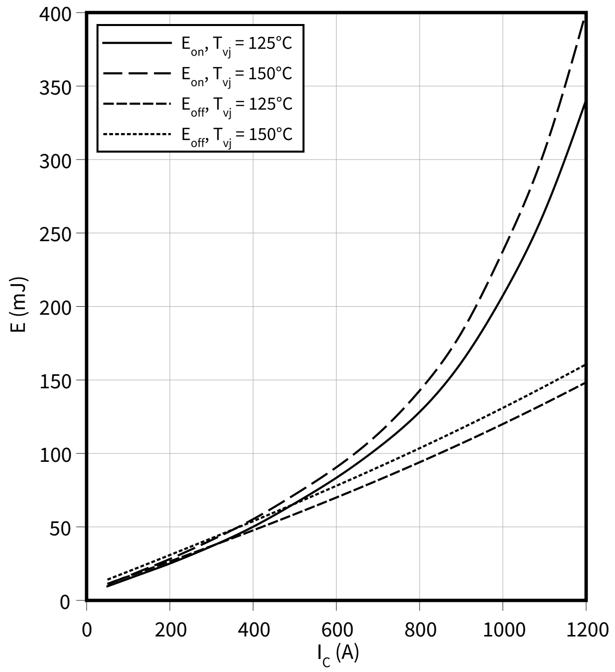
$V_{CE} = 20$ V



Switching losses (typical), IGBT, Inverter

$E = f(I_C)$

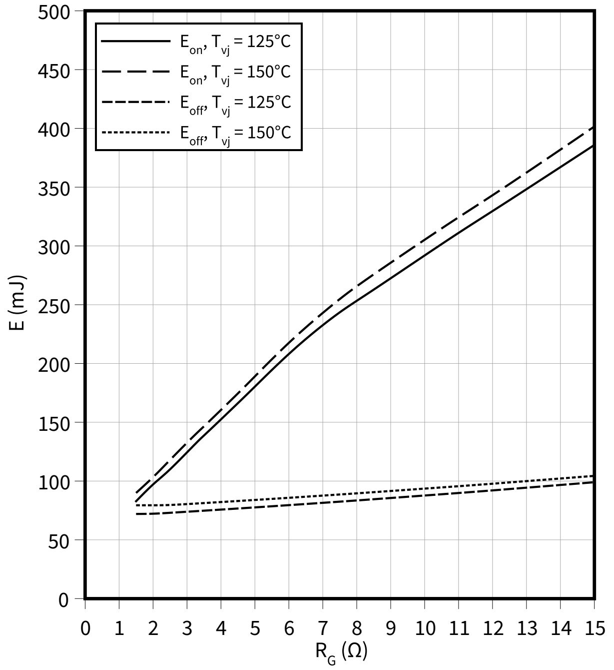
$R_{Goff} = 1.5\ \Omega$, $R_{Gon} = 1.5\ \Omega$, $V_{GE} = \pm 15$ V, $V_{CC} = 600$ V



Switching losses (typical), IGBT, Inverter

$E = f(R_G)$

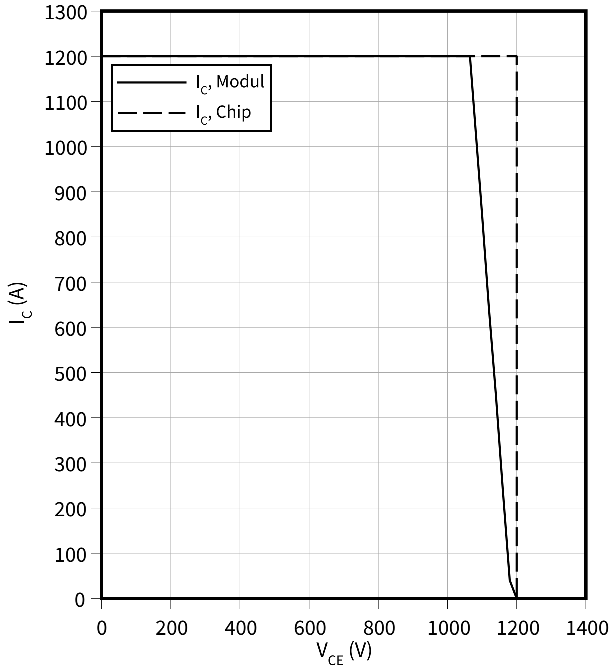
$V_{GE} = \pm 15\ V$, $I_C = 600\ A$, $V_{CC} = 600\ V$



Reverse bias safe operating area (RBSOA), IGBT, Inverter

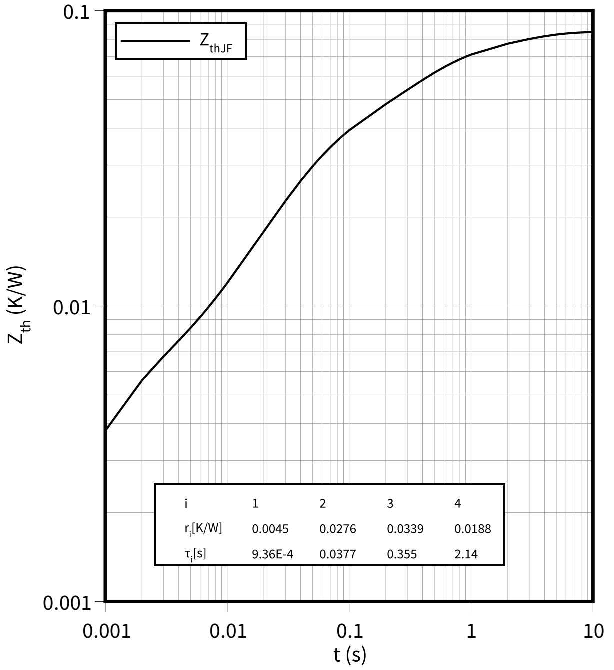
$I_C = f(V_{CE})$

$R_{Goff} = 1.5\ \Omega$, $V_{GE} = \pm 15\ V$, $T_{vj} = 150\ °C$



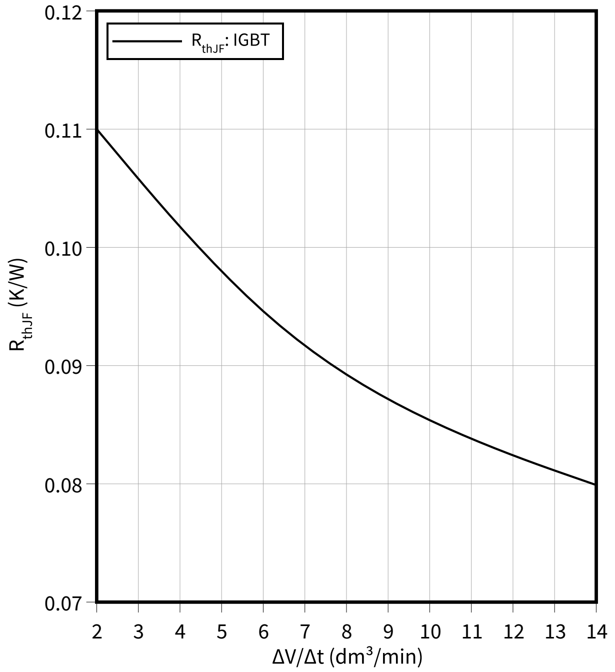
Transient thermal impedance, IGBT, Inverter

$Z_{th} = f(t)$



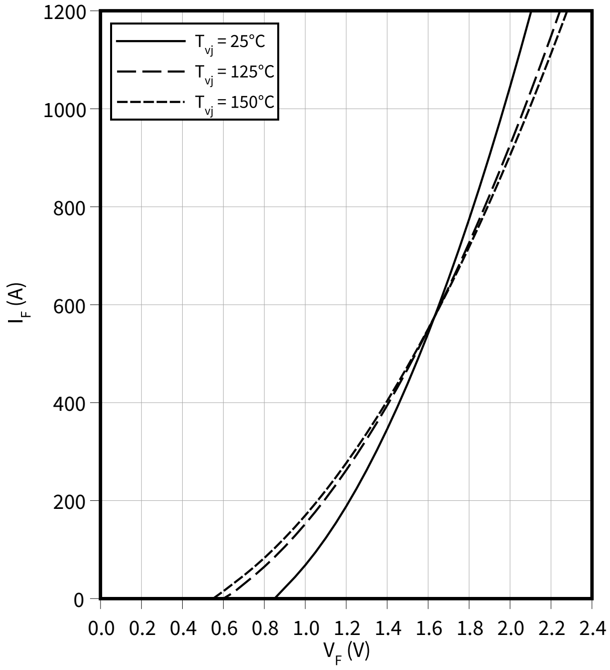
Thermal impedance, IGBT, Inverter

$R_{thJF} = f(\Delta V/\Delta t)$



Forward characteristic (typical), Diode, Inverter

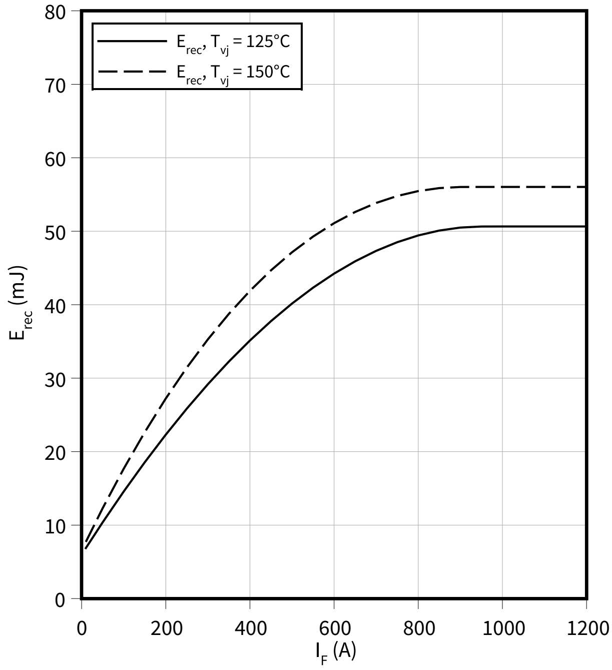
$I_F = f(V_F)$



Switching losses (typical), Diode, Inverter

$E_{rec} = f(I_F)$

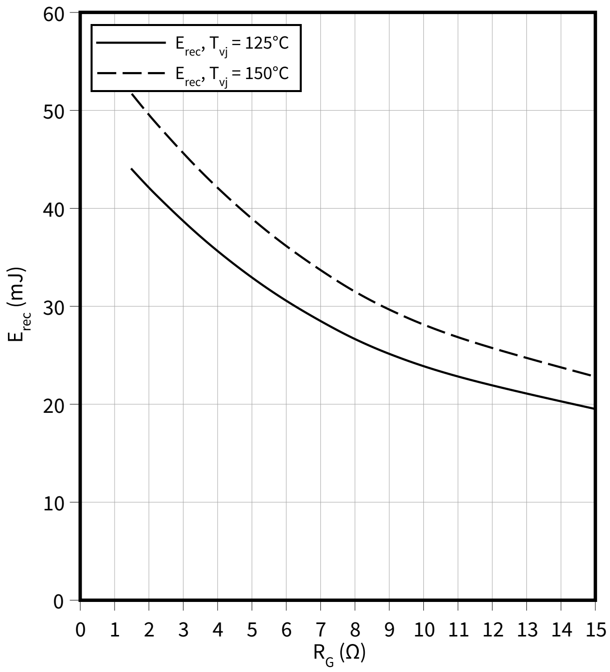
$R_{Gon} = 1.5\ \Omega$, $V_{CC} = 600$ V



Switching losses (typical), Diode, Inverter

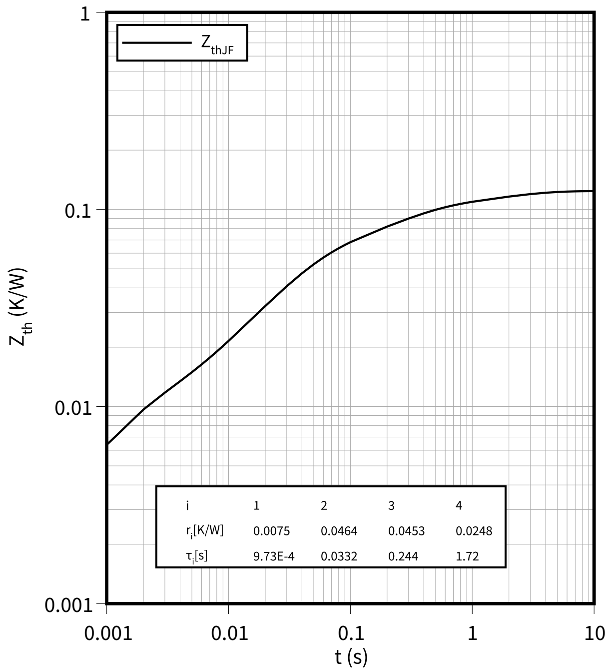
$E_{rec} = f(R_G)$

$I_F = 600$ A, $V_{CC} = 600$ V



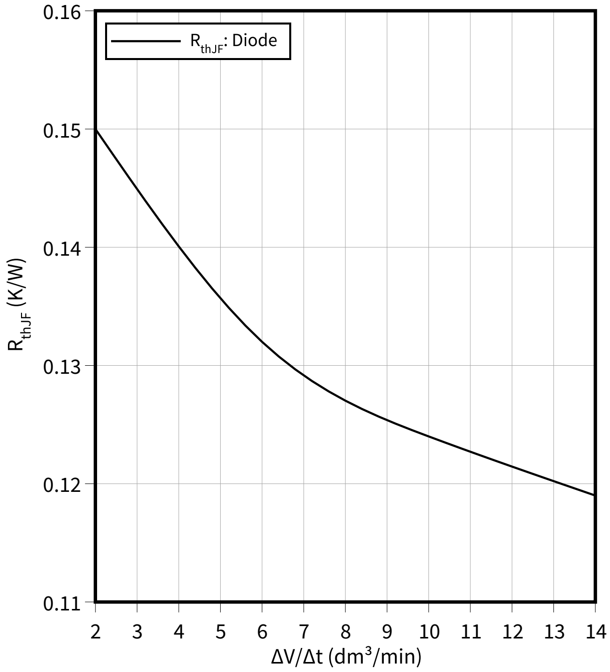
Transient thermal impedance, Diode, Inverter

$Z_{th} = f(t)$

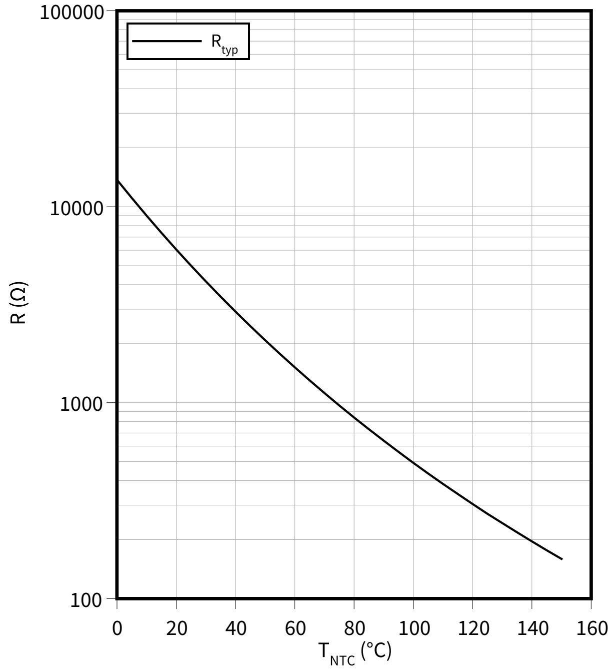


i	1	2	3	4
r_i[K/W]	0.0075	0.0464	0.0453	0.0248
τ_i[s]	9.73E-4	0.0332	0.244	1.72

Thermal impedance, Diode, Inverter
$R_{thJF} = f(\Delta V/\Delta t)$



Temperature characteristic (typical), NTC-Thermistor
$R = f(T_{NTC})$



6 Circuit diagram

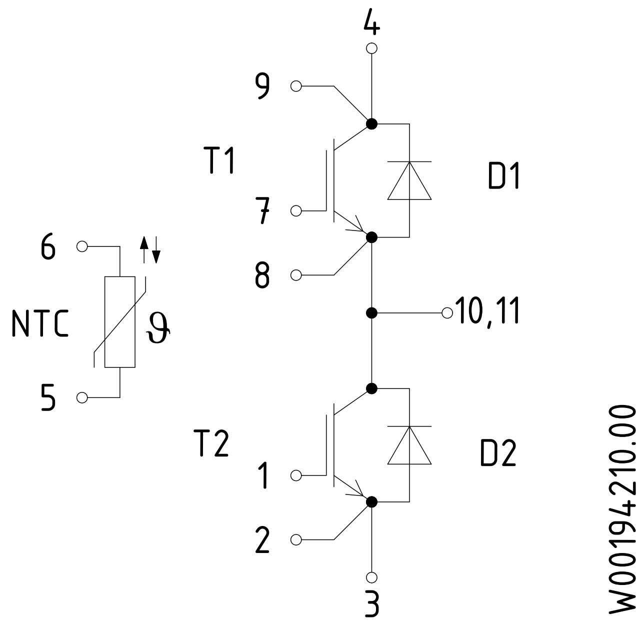


Figure 1

7 Package outlines

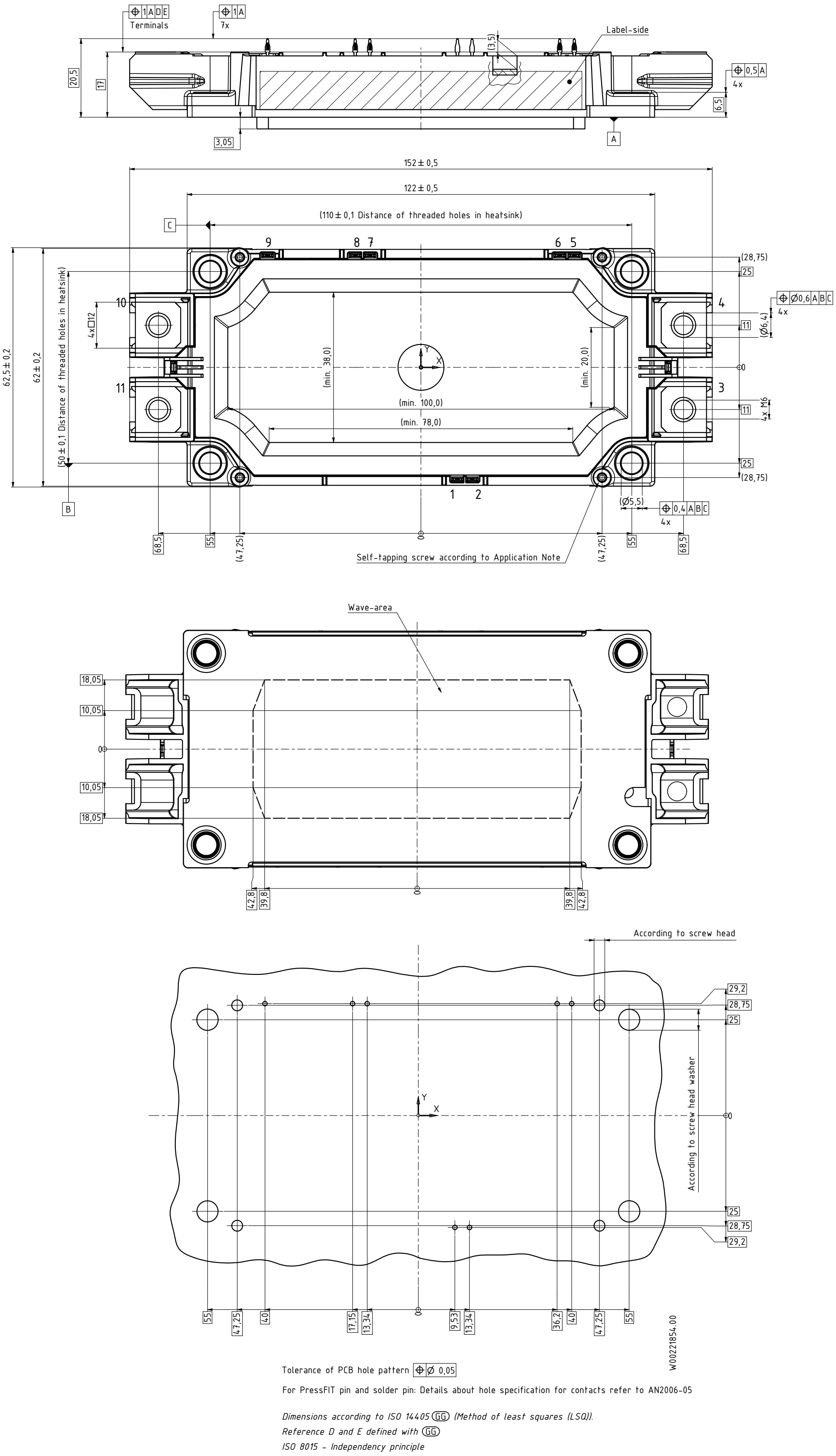


Figure 2

8 Module label code

Module label code		
Code format	Data Matrix	Barcode Code128
Encoding	ASCII text	Code Set A
Symbol size	16x16	23 digits
Standard	IEC24720 and IEC16022	IEC8859-1

Code content	*Content*	*Digit*	*Example*
	Module serial number	1 – 5	71549
	Module material number	6 - 11	142846
	Production order number	12 - 19	55054991
	Date code (production year)	20 – 21	15
	Date code (production week)	22 – 23	30

Example	71549142846550549911530	71549142846550549911530

Figure 3

Revision history

Document revision	Date of release	Description of changes
V1.0	2019-11-26	Target datasheet
n/a	2020-09-01	Datasheet migrated to a new system with a new layout and new revision number schema: target or preliminary datasheet = 0.xy; final datasheet = 1.xy
0.10	2021-08-30	Target datasheet
1.00	2022-04-01	Final datasheet
1.10	2024-03-15	Final datasheet

Trademarks

All referenced product or service names and trademarks are the property of their respective owners.

Edition 2024-03-15

Published by

Infineon Technologies AG

81726 Munich, Germany

Do you have a question about any aspect of this document?

Email: erratum@infineon.com

Document reference
IFX-AAY258-004